

Update Notification
Document #: FPCN20904X1
Issue Date: 8 July 2015

Title of Change:	Update Notice of FPCN20904X to remove ESD8104MUTAG device.
Proposed first ship date:	3 September 2015
Contact information:	Contact your local ON Semiconductor Sales Office or Norhayati.Othman <norhayati.othman@onsemi.com></norhayati.othman@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Chean Ching Sim <cheanshing.sim@onsemi.com>.</cheanshing.sim@onsemi.com>
Type of notification:	ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other
Change Sub-Category(s):       □ Datasheet/Product Doc change         ☑ Manufacturing Site Change/Addition       □ Material Change       □ Shipping/Packaging/Marking         □ Manufacturing Process Change       □ Other:	
Sites Affected: ☐ All site(s) ☐ not ap	plicable ON Semiconductor site(s): External Foundry/Subcon site(s) Advanced Semiconductor Engineering Shanghai
Description and Purpose:	
FPCN20904X announce the addition of Advance Semiconductor Engineering (ASE) Shanghai, China as qualified assembly site for QFN devices.	
This UN is issued to remove ESD8104MUTAG from FPCN20904X. The ESD8104MUTAG will not undergo this change and will continue to be assembled at Seremban Malaysia (SBN).	
List of Affected Standard Parts:	
ESD8104MUTAG	

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